

ON Semiconductor
Formerly a Division of Motorola



Subject: Motorola PRODUCT AND PROCESS CHANGE NOTIFICATION 4495

TITLE: SMALL BLOCK WAFER SITE CHANGE

EFFECTIVE DATE: 05-JUN-99

AFFECTED CHANGE CATEGORIES
Motorola Fab Site

AFFECTED PRODUCT DIVISIONS
GENERAL PURPOSE PRO

ADDITIONAL RELIABILITY DATA: Available
Contact your local Motorola Sales Office.

Ref: RBX690

SAMPLES: Contact Below
Contact your local Motorola Sales Office.

Ref: RPV290@email.sps.mot.com

For any questions concerning this notification:
REFERENCE: BILL ROMAN PHONE: 602-413-3824

DISCLAIMER:

MOTOROLA WILL CONSIDER THIS CHANGE APPROVED UNLESS SPECIFIC
CONDITIONS OF ACCEPTANCE ARE PROVIDED IN WRITING WITHIN 30 DAYS OF
RECEIPT OF THIS NOTICE. TO DO SO, CONTACT YOUR LOCAL MOTOROLA SALES
OFFICE.

GPCN FORMAT: CUSTOMER

DO NOT REPLY TO THIS MESSAGE.

PRODUCT AND PROCESS CHANGE NOTIFICATION

ISSUE DATE: 25-Feb-1999

NOTIFICATION #:4495

EFFECTIVE DATE: 05-Jun-1999

ISSUING DIVISION:PHX-GPPD

DESCRIPTION AND PURPOSE

This is advanced notice of our relocating the wafer process on the MDC3105LT1, MDC3105LT3 and MDC3205RLRP from our Bipolar 5 wafer facility in Phoenix, Arizona, to our ISMF facility located in Seremban, Malaysia. The ISMF facility has been in volume production on similar products with the same wafer technology for more than five years. Final assembly and test will not change.

QUALIFICATION PLAN

Generic reliability data plus product characterization will be used to qualify these products in ISMF.

RELIABILITY DATA SUMMARY

Data to be supplied with product samples on April 15, 1999.

ELECTRICAL CHARACTERISTIC SUMMARY

Characterization data will be available April 15, 1999.

CHANGED PART IDENTIFICATION

All products with a Date Code of April 17 and beyond will be the only indication of this change.

FILE FORMAT: ASCII TEXT

FONT - Courier

SIZE - 12 Point

LINE - 70 characters/line

PAGE - 55 lines/page

PAGEBREAK CHARACTER - ^L (Control L)

AFFECTED DEVICE LIST (WITHOUT SPECIALS)

MDC3105LT1 , MDC3105LT3 , MDC3205RLRP